Product / Process Change Notification

N° 2015-067-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Change of wafer fab and wafer test from DOPL 6 inch Villach to DOPL 8 inch Kulim and standardization of bondwire diameter and wafer thickness affecting TLE4274GS V25 and TLE4274GS V33

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **08. November 2016.**
- Infineon aligns with the widely-recognized JEDEC STANDARD**"JESD46", which stipulates:**
  "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Product / Process Change Notification

N° 2015-067-A

▸ Products affected:

Sales Name	SP N°	OPN	Package
TLE4274GS V25	SP000395822	TLE4274GSV25HTSA1	PG-SOT223-4
TLE4274GS V33	SP000396456	TLE4274GSV33HTSA1	PG-SOT223-4

▸ Detailed Change Information:

Subject: Change of wafer fab and wafer test to Kulim and wafer diameter to 8 inch and standardization of bondwire diameter and wafer thickness affecting TLE4274GS V25 and TLE4274GS V33.

Reason: Due to continuously raising demand for Infineon automotive products we have to implement the well-known FE location Kulim as 8 inch wafer fab and wafer test location.

The bondwire diameter has been standardized to 38µm and the wafer thickness to 215 µm.

Description:	Old	New
Wafer diameter	■ 6 inch	■ 8 inch
Wafer thickness	■ 150 µm	■ 215 µm
Bondwire diameter	■ For TLE4274GS V33: 50 µm Au ■ For TLE4274GS V25: 38 µm Au	■ For TLE4274GS V33: 38 µm Au ■ For TLE4274GS V25: 38 µm Au
Wafer fab location	■ Infineon Technologies Austria AG, Villach, Austria	■ Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia
Wafer test location	■ Infineon Technologies Austria AG, Villach, Austria	■ Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia

▸ Product Identification:

Wafer lot numbers from Villach start with VExxxxxx

and from Kulim with 1Exxxxxx

Traceability assured via date code.

SP ordering number is different

▸ Impact of Change:

No impact on electrical performance. Quality and reliability verified by qualification.
There is no change in form, fit and function except above specified changes.

▸ Attachments:

N.A.

Time Schedule:

Final qualification report:	available
First samples available:	available
Intended start of delivery:	01-April-2017 or earlier after customer release

Refer to page 4/4:

Last order date of unchanged product:	31-March-2017
Last delivery date of unchanged product:	30-September-2017

If you have any questions, please do not hesitate to contact your local Sales office.

PRODUCT REPLACEMENT

Referring to PCN N° 2015-067-A

🟥 Last order date of unchanged product:	2017-03-31
🟥 Last delivery date of unchanged product:	2017-09-30

CURRENT				**NEW (REPLACEMENT)**			
Device	**Ordering Code**	**OPN**	**Package**	**Device**	**Ordering Code**	**OPN**	**Package**
TLE4274GS V25	SP000395822	TLE4274GSV25HTSA1	PG-SOT223-4	TLE4274GS V25	SP001130106	TLE4274GSV25HTSA2	PG-SOT223-4
TLE4274GS V33	SP000396456	TLE4274GSV33HTSA1	PG-SOT223-4	TLE4274GS V33	SP001130104	TLE4274GSV33HTSA2	PG-SOT223-4